

<b>Title of Change:</b>	SOT23 BAS40 series Schottky device upgrade mask set to optimize the die per wafer quantity.
<b>Effective date:</b>	20 Jan 2022
<b>Contact information:</b>	Contact your local onsemi Sales Office
<b>Type of notification:</b>	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
<b>Change Category:</b>	Wafer Fab Change
<b>Change Sub-Category(s):</b>	Material Change

<b>Sites Affected:</b>	
<b>onsemi Sites</b>	<b>External Foundry/Subcon Sites</b>
onsemi, ISMF Malaysia	None

**Description and Purpose:**

Changes to reduce the saw street and non-active elements in the die, not impacting any electrical performance of the die.

There will no changes on finish package material and performance will be same as before changes.

The purpose of this changes is to optimize the die per wafer quantity.

**List of Affected Standard Parts:**

***Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).*

BAS40-04LT1G	SBAS40-04LT1G	SBAS40-06LT1G
SBAS40LT1G	SBAS40LT3G	BAS40LT1G
BAS40-06LT1G		